



Course material

Course:

Micro and Nanofabrication (MEMS)

Video:

7.2 Inspection and metrology 2

Concepts (extracted from automatically generated subtitles):

Silicon dioxide. Intensity wavelength. Exact thickness. Wafer inspection. Often used tool. Optical measurements. Polarization of the reflected light. Thin films. Layer thickness. Curve here. Polychromatic light. Silicon wafers. Illumination spot. Function of the sio. Optical methods.



[to video sequence search](#)
(within Micro and Nanofabrication (MEMS).)



[to video](#)

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<https://www.epfl.ch/education/educational-initiatives/cede/educational-technologies-gallery/boocs-en/>
page 1/13



Inspection and metrology 2

Optical thin film thickness measurement

Micro and Nanofabrication (MEMS)

Prof. Jürgen Brugger & Prof. Martin A. M. Gijs

...

notes

summary

0m 0s





- Physical principle
- Variations
 - Reflectometer & transmittometer
 - Ellipsometer
- Bi-morph SiO_2 thickness measurement

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In wafer inspection, metrology and quality control,

notes

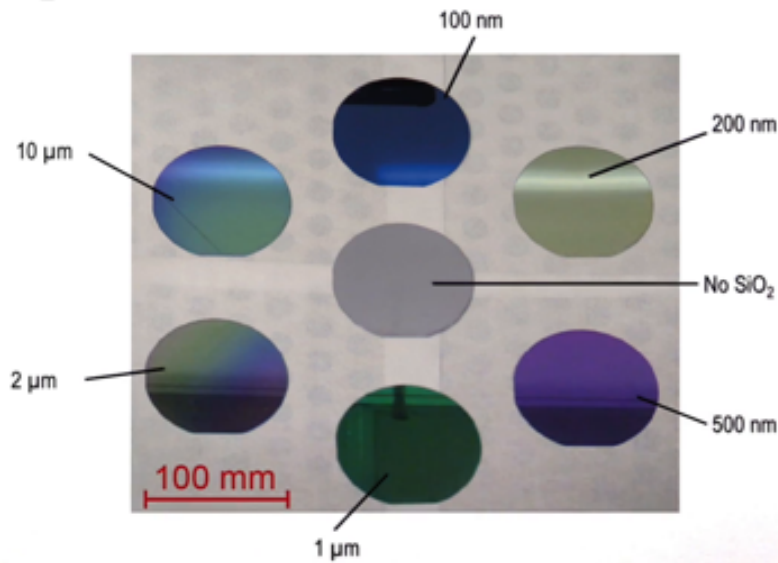
summary

0m 1s



Color change in SiO₂ thin film

SiO₂ on silicon



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it is very important to determine the exact thickness of deposited thin films. Here in this lesson, I will show how we can precisely quantify the thickness of transparent films such as silicon dioxide or silicon nitrate using optical methods. We will use again the bi-morph device as an example and determine the SiO₂ thickness. Remember, we have already seen these silicon dioxide coated silicon wafers in an earlier lesson. Pay again attention to the different colors appearance which is a function of the SiO₂ layer thickness. This effect is due to the interference between the light reflected by the upper

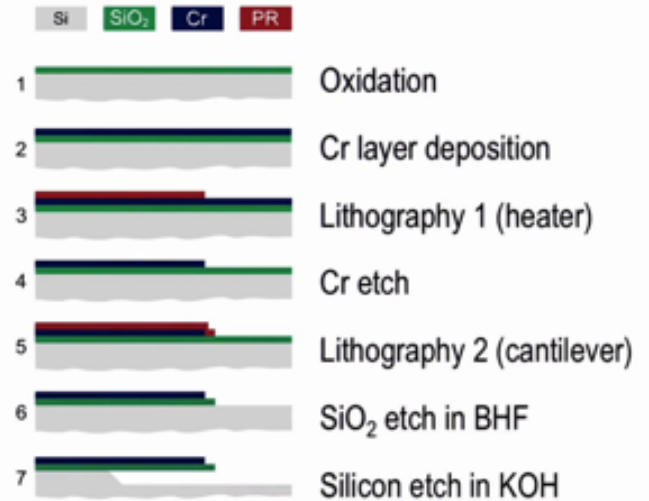
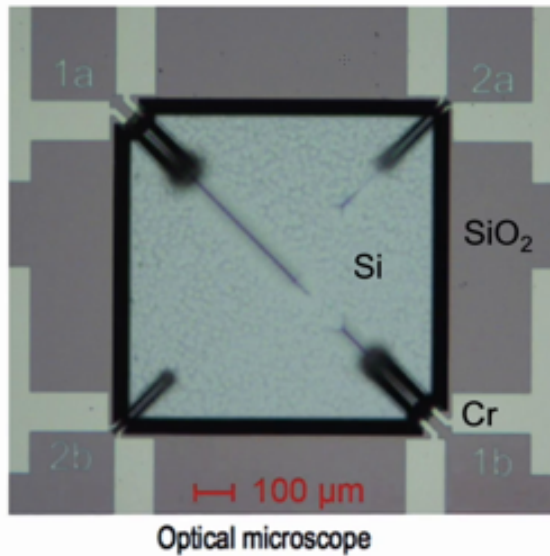
notes

summary

0m 5s



Bi-morph SiO_2 thickness measurement



How to measure the thickness of SiO_2 ?

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and lower boundaries of the transparent thin films. It allows already getting a first estimation of the SiO_2 thickness. For more precise value, we need specific tools.

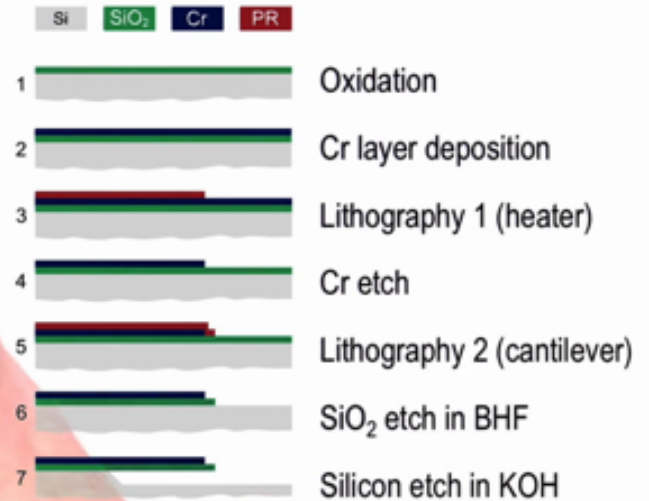
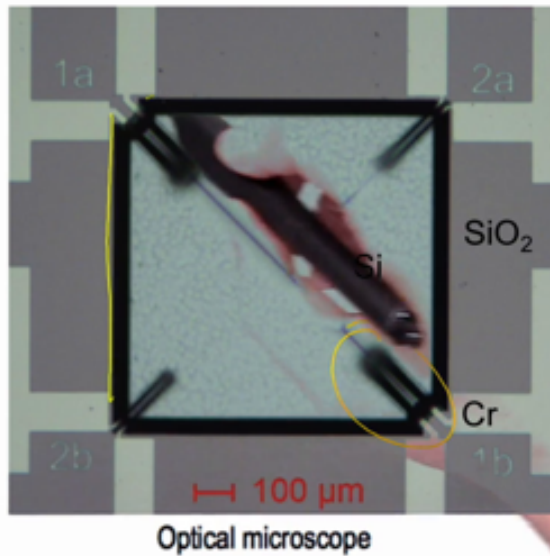
notes

summary

0m 49s



Bi-morph SiO₂ thickness measurement



How to measure the thickness of SiO₂?

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I will now show you how we can determine the SiO₂ layer thickness of the bi-morph device shown here again. The SiO₂ layer not only defines the mechanical properties of the free standing bi-morph cantilever, over here,

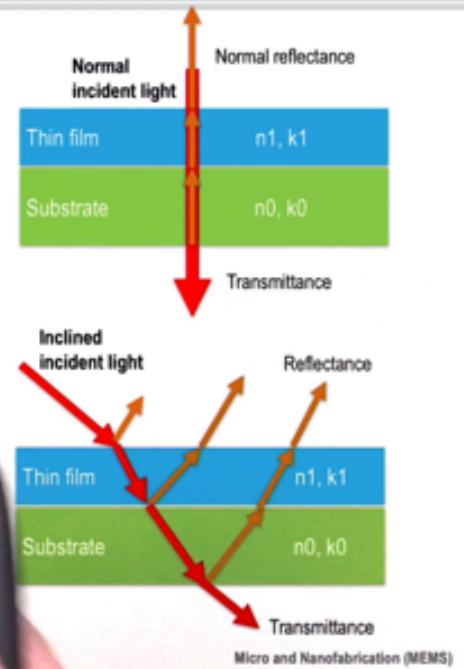
notes

summary

1m 2s



- Polychromatic incident light \rightarrow reflectance/transmittance spectrum \rightarrow thin film thickness with the best spectrum fitting
- The light properties change of reflected/transmitted light is correlated to the thin film thickness
- Thin film has to be "transparent" to incident light
- Measurement for multiple thin film layers is also possible
- Non-destructive measurement



but it also delineates the mask layer for the KOH etching like here, here , here and here. Finally, the SiO₂ layer also serves as an electrical isolation between the conducting chrome wires and the underlying silicon substrate. There are 2 ways to perform optical measurements shown here and that use polychromatic light

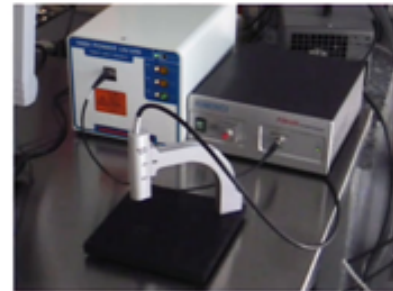
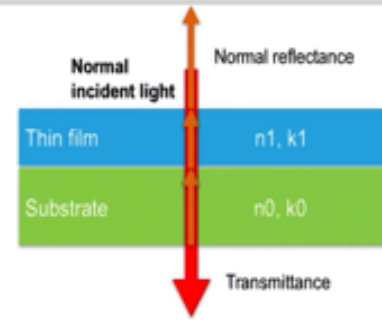
notes

summary

1m 24s



- Normal incidence
- Signal: change in intensity over the wavelength
- Light source: deuterium lamp + halogen lamp
(wavelength: 200nm to 1100nm)
- Beam spot size: 1.5mm
- Film thickness range: 1nm to 40 μ m
- Thin film material: photoresist, SiO₂, Si₃N₄ and other polymer, dielectric films
- n, k measurement is also possible



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that is incident to the surface either normal or under an angle. The light is then reflected back to the instrument and by measuring intensity wavelength, or polarization of the reflected light, one can compute the thin film properties. For instance by knowing the film parameters of "n" and "k", where "n" is the refractive index, and "k" is the extension coefficient respectively, one can precisely determine the SiO₂ layer thickness. It is also possible to measure multiple thin films. These techniques are entirely non-destructive to the sample. An equipment to measure the layer thickness of thin films using the normal incidence mode is called reflectometer or transmittometer as shown here on the right side.

notes

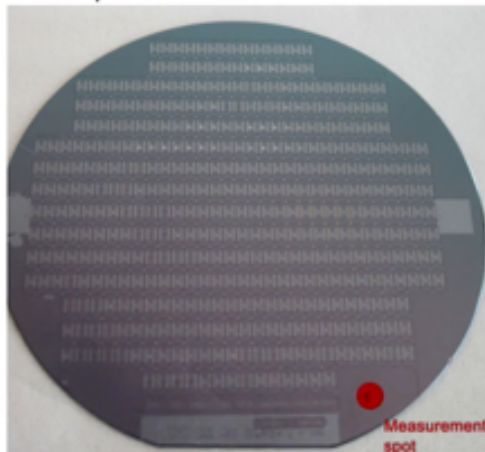
summary

1m 49s

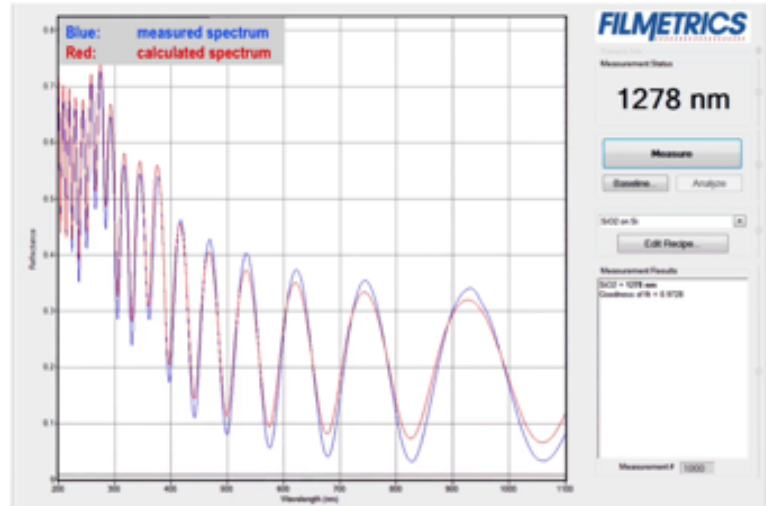


Bi-morph SiO_2 thickness measurement

Bi-morph wafer



Spot size is too large to measure the SiO_2 in the Bi-morph die
→ measure the SiO_2 at wafer edge



SiO_2 thickness: 1278nm (1500nm in design)
Goodness of fit: 0.9728 (1 means perfect fitting)

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It is based on illuminating the surface with polychromatic light of wavelength between 200 and 1100nm. The reflectometer detects the change in intensity of the reflected light over the light source spectrum. Intensity variations are due to thin film interferences. The illumination spot is in the order of 1.5 mm as a consequence, only large film samples can be measured. The range of thickness measurement is between 1 nm and 40 μm . This is quite a wide range. This method is often used on photoresists, SiO_2 , silicon nitrate, glass, and polymer samples. It also allows determining "n" and "k" values, in case the thickness is already known. Please consult accompanying documents for more physics background of this measurement. Let us take again the wafer in process for the bi-morph device, shown here. you apply this method at the border of the wafer, here, where there is a large enough surface area to place the measurement spot. In this particular case, we measure the SiO_2 layer thickness after the KOH etching. Remember that the target value for the SiO_2 layer is 1.5 μm . We also know that the SiO_2 serves as a mask for the KOH etching. But that the SiO_2 is also etched slowly in the KOH etch part. Hence, we expect to see a reduced thickness of the SiO_2 . Let's now verify this here. The curve here, shows the reflectance on the "y" axis as a function of the wavelength on the "x" axis. This spectrum shows a wavy curve as shown here,

notes

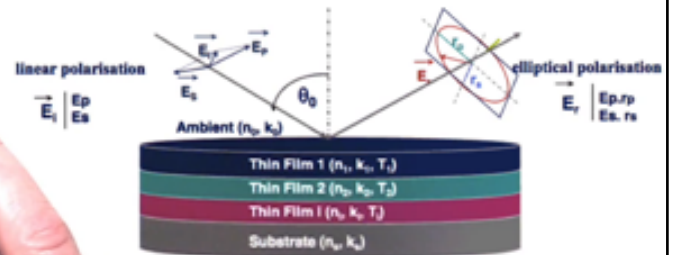
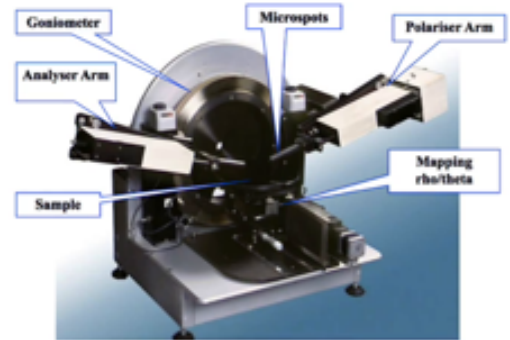
summary

2m 37s



Spectroscopic ellipsometer

- Inclined incidence
- Change in polarization after reflection
- Spot size: 400 μm
- Wavelength range: 190nm to 2000nm
- Film thickness range: few Å to 50 μm
- Other properties of thin film:
 - Composition
 - Roughness
 - n, k value
- ZnO, Pbs, PbSe, TiO₂, Al, Ag, Au, SiN, SiC, Si, CdTe, CdS...



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which is then fitted mathematically to determine the SIO2 thickness. In our case, we get 1.278 μm which is with the goodness of fit of nearly 1. As expected, the thickness of SIO2 has been reduced from our initial value of 1.5 μm to 1.278 μm . The 200 nm difference obtained is expected and is due to the loss of SIO2 during the KOH silicon etch. Another often used tool is the spectroscopic ellipsometer. Here, the angle of light incident is inclined which induces a polarization change after the reflection. The linear polarization of the incoming light is changed to elliptical polarization for the reflected light. The spot size of the light is in the order of 400 μm . And can be aligned to a microstructure if needed. The wavelengths can be varied between 190 nm and 2000 nm,

notes

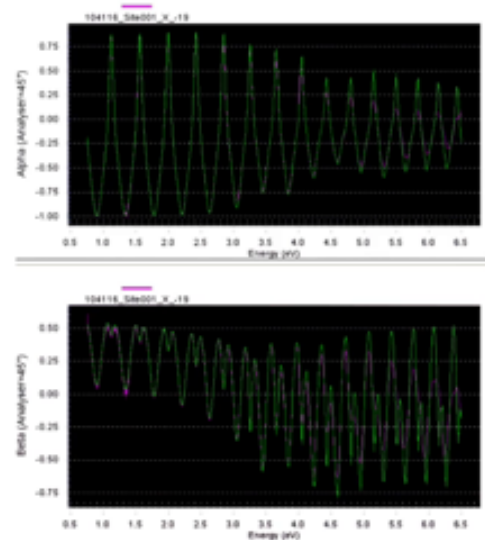
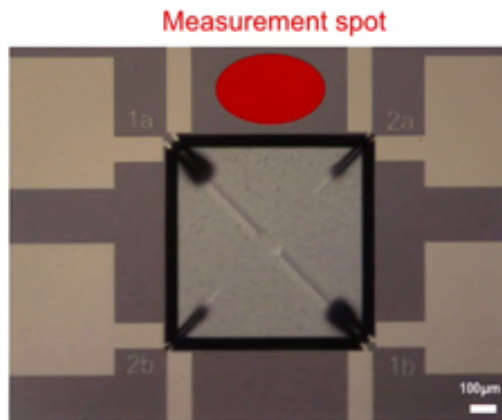
summary

4m 25s



Bi-morph SiO_2 thickness measurement

- Use ellipsometer to measure SiO_2 in the Bi-morph die



SiO_2 thickness: 1282nm (1500nm in design)
Goodness of fit: 0.9585 (1 means perfect fitting)

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which allows measuring film thickness from a few Angstroms up to 50 µm thickness. The tool also allows determining to some extent the composition roughness and "n" and "k" values, where "n" is a real, and "k" is the imaginary part of the refractive index. It can be applied to a variety of dielectric optically transparent thin films, and even some metal thin films. Please consult the study material for further data on the basics behind this method.

notes

summary

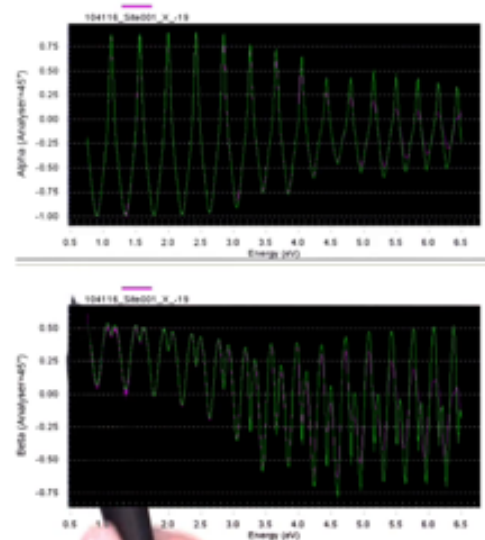
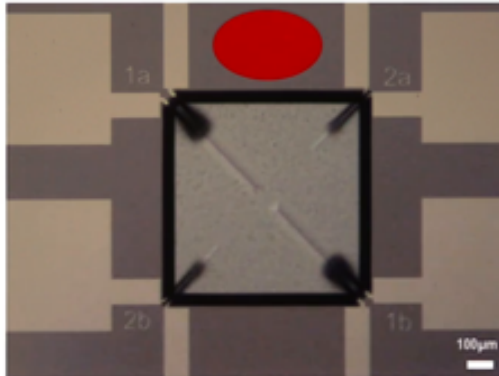
5m 25s



Bi-morph SiO_2 thickness measurement

- Use ellipsometer to measure SiO_2 in the Bi-morph die

Measurement spot



SiO_2 thickness: 1282nm (1500nm in design)
Goodness of fit: 0.9585 (1 means perfect fitting)

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As before, I show you now how to use the ellipsometer to measure SiO_2 layer thickness in the bi-morph ship area. The spot size is small enough to measure the SiO_2 thickness at the border of the device like shown here.

notes

summary

5m 55s





- Reflectometer & Transmittometer
 - Rapid measurement of thin film thickness
 - Large beam spot size
- Ellipsometer
 - Smaller beam size and higher accuracy
 - More complicated methodology
- Both are non-contact, non-invasive
- No sample preparation needed

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The two curves here, showing the "y" axis, the "Alpha" and the "Beta" parameter, for an angle of 45 degree and as a function of wavelength here shown in eV units. The parameters alpha and beta in y axis of the spectrum are called ellipse parameters. They are composed of the incident angle and some geometric factors that describe the shape of elliptically polarized light after the reflection. The measurement here results in 1282 nm, which agrees very well the data obtained from the reflectometer. In this module, I have introduced 2 optical techniques to determine the thin film thickness. The reflectometer allows us a quick and simple measurement. For more precise measurement, it is advised to use the ellipsometer. Both of them do not touch and damage the sample, and no sample preparation is required.

notes

summary

6m 13s

